

-	6	((cvp cmp polish\$3 etch\$3) and (dummy near (holder stage platform platen wafer))) and (((359/509).CCLS.) ((250/431,428).CCLS.) ((356/36).CCLS.) ((156/345.12,345.13,345.15).CCLS.))	USPAT; US-PGPUB	2003/08/10 20:38
-	23	((cvp cmp polish\$3 etch\$3) and (dummy near (holder stage platform platen wafer))) and (lens same (housing chamber))	USPAT; US-PGPUB	2003/08/10 20:42
-	23	((((cvp cmp polish\$3 etch\$3) and (dummy near (holder stage platform platen wafer))) and (lens same (housing chamber))) not (((cvp cmp polish\$3 etch\$3) and (dummy near (holder stage platform platen wafer))) and (((359/509).CCLS.) ((250/431,428).CCLS.) ((356/36).CCLS.) ((156/345.12,345.13,345.15).CCLS.))	USPAT; US-PGPUB	2003/08/10 20:42
-	5807	((cvp cmp polish\$ etch\$) and (lens same (housing chamber)))	USPAT; US-PGPUB	2003/08/10 20:51
-	672	((((cvp cmp polish\$ etch\$) and (lens same (housing chamber)))) and ((first second\$3 primary another other two) near (platen platform stage support chuck)))	USPAT; US-PGPUB	2003/08/10 20:52
-	1	((((359/509).CCLS.) ((250/431,428).CCLS.) ((356/36).CCLS.) ((156/345.12,345.13,345.15).CCLS.)) and (((cvp cmp polish\$ etch\$) and (lens same (housing chamber)))) and ((first second\$3 primary another other two) near (platen platform stage support chuck)))	USPAT; US-PGPUB	2003/08/10 20:53
-	242	(((((cvp cmp polish\$ etch\$) and (lens same (housing chamber)))) and ((first second\$3 primary another other two) near (platen platform stage support chuck))) and (nitrogen inert))	USPAT; US-PGPUB	2003/08/10 20:53
-	160	(((((cvp cmp polish\$ etch\$) and (lens same (housing chamber)))) and ((first second\$3 primary another other two) near (platen platform stage support chuck))) and (nitrogen inert)) and (extract\$ exhaust)	USPAT; US-PGPUB	2003/08/10 20:53
-	56	(((((cvp cmp polish\$ etch\$) and (lens same (housing chamber)))) and ((first second\$3 primary another other two) near (platen platform stage support chuck))) and (nitrogen inert)) and (extract\$ exhaust)) and nozzle	USPAT; US-PGPUB	2003/08/10 20:55
-	51	((((((cvp cmp polish\$ etch\$) and (lens same (housing chamber)))) and ((first second\$3 primary another other two) near (platen platform stage support chuck))) and (nitrogen inert)) and (extract\$ exhaust)) and nozzle) and valve	USPAT; US-PGPUB	2003/08/10 20:55
-	46	5669979.URPN.	USPAT	2004/05/12 16:10
-	76	5571366.URPN.	USPAT	2004/05/12 16:14
-	222	(wafer same (dummy reference gold\$2)) and (lens and nozzle)	USPAT	2004/05/12 16:17
-	16	((wafer same (dummy reference gold\$2)) and (lens and nozzle)) and ((other another differ\$ two second\$3) near nozzle)	USPAT	2004/05/12 16:20
-	16	((wafer same (dummy reference gold\$2)) and (lens and nozzle)) and ((other another differ\$ two second\$3 dual) near nozzle)	USPAT	2004/05/12 16:36
-	564	wafer and ((other another differ\$ two second\$3 dual) near nozzle)	USPAT	2004/05/12 16:24

-	171	(wafer and ((other another differ\$ two second\$3 dual) near nozzle)) and exhaust\$	USPAT	2004/05/12 16:21
-	14	((wafer and ((other another differ\$ two second\$3 dual) near nozzle)) and exhaust\$) and lens	USPAT	2004/05/12 16:21
-	87	(wafer and ((other another differ\$ two second\$3 dual) near nozzle)) and cmp	USPAT	2004/05/12 16:31
-	60	("3649509" "3727620" "3770598" "4027686" "4092176" "4110176" "4113492" "4315059" "4326940" "4336114" "4376685" "4405416" "4428815" "4435266" "4489740" "4510176" "4518678" "4519846" "4529353" "4693805" "4732785" "4789445" "4981715" "5039381" "5055425" "5092975" "5100502" "5155336" "5162260" "5222310" "5224504" "5230743" "5252807" "5256274" "5259407" "5290361" "5316974" "5328589" "5344491" "5349978" "5368711" "5377708" "5382885" "5415890" "5429733" "5447615" "5516412" "5608943" "5625170" "5651865" "5705223" "5718813" "5723028" "5811951" "5975834" "6071388" "6093291" "6136163" "6254760" "6258220").PN.	USPAT	2004/05/12 16:25
-	1903	array near nozzle	USPAT	2004/05/12 16:31
-	255	(array near nozzle) and wafer	USPAT	2004/05/12 16:31
-	97	(array near nozzle) and (wafer same (clean\$ polish\$))	USPAT	2004/05/12 16:31
-	353	lens and ((other another differ\$ two second\$3 dual) near nozzle)	USPAT	2004/05/12 16:36
-	169	(lens and ((other another differ\$ two second\$3 dual) near nozzle)) and (wafer semiconductor\$ substrate)	USPAT	2004/05/12 16:37
-	11	((wafer substrate semiconductor\$) near clean\$) and (separate near nozzle)	USPAT	2004/05/12 16:43
-	72	platen near chuck	USPAT	2004/05/12 17:02
-	40	(platen near chuck) same wafer	USPAT	2004/05/12 17:06
-	17	(laser near clean\$) and ((reference standard\$ dummy gold\$2) near (wafer semiconductor\$ substrate))	USPAT	2004/05/12 17:17
-	150	(laser same clean\$) and ((reference standard\$ dummy gold\$2) near (wafer semiconductor\$ substrate))	USPAT	2004/05/12 17:17
-	133	((laser same clean\$) and ((reference standard\$ dummy gold\$2) near (wafer semiconductor\$ substrate))) not ((laser near clean\$) and ((reference standard\$ dummy gold\$2) near (wafer semiconductor\$ substrate)))	USPAT	2004/05/12 17:22
-	12	4512659.URPN.	USPAT	2004/05/12 17:20
-	46	(calibrat\$ near wafer) same (support holder platen chuck stage)	USPAT	2004/05/12 17:22
-	183	(wafer same (clean\$ process\$3)) and ((exhaust vacuum evacuat\$) same venturi)	USPAT;	2004/05/12 17:42
-	46	((wafer same (clean\$ process\$3)) and ((exhaust vacuum evacuat\$) same venturi)) and cmp	USPAT;	2004/05/12 17:42
-	4	((wafer same (clean\$ process\$3)) and ((exhaust vacuum evacuat\$) same venturi)) and (laser same clean\$)	USPAT;	2004/05/12 17:42

L Number	Hits	Search Text	DB	Time stamp
127	219	(359/509).CCLS.	USPAT; US-PGPUB	2004/05/17 10:16
128	461	(356/36).CCLS.	USPAT; US-PGPUB	2004/05/17 10:16
129	454	(156/345.12,345.13,345.15).CCLS.	USPAT; US-PGPUB	2004/05/17 10:16